

REMARKS/ARGUMENTS

Claims 16-25 are pending in this application. By this Amendment, Applicant amends the Title of the Invention and the Abstract of the Disclosure and cancels Claims 26-33.

Claims 26-33 have been canceled because these claims are directed to a non-elected invention. Applicant reserves the right to file a Divisional Application to pursue prosecution of non-elected Claims 26-33.

Non-elected Claims 23-25 are dependent upon generic Claim 16. Accordingly, Applicant respectfully requests that the Examiner rejoin and allow Claims 23-25 when generic Claim 16 is allowed.

Applicant notes that an Information Disclosure Statement was filed on July 2, 2009. Accordingly, Applicant respectfully requests that the Examiner include an initialed and signed Form PTO/SB/08a which indicates that each of the reference cited therein have been entered and considered with the next Office Action.

The Title of the Invention was objected to for allegedly not being descriptive. Applicant has amended the Title of the Invention as suggested by the Examiner. Accordingly, Applicant respectfully requests reconsideration and withdrawal of this objection.

The Abstract of the Disclosure was objected to because the elected and claimed invention is directed to a method, whereas the Abstract describes an apparatus. Applicant has amended the Abstract of the Disclosure to describe a method. Accordingly, Applicant respectfully requests reconsideration and withdrawal of this objection.

Claims 16-22 were rejected under 35 U.S.C. § 102(b) as being anticipated by Sakamoto et al. (U.S. 6,228,196). Applicant respectfully traverses the rejection of Claims 16-22.

Claim 16 recites:

A method for manufacturing a chip electronic component-mounted ceramic substrate, comprising the steps of:

mounting a chip electronic component including a ceramic sintered compact defining an element assembly and terminal electrodes on a ceramic green body having conductors thereon such that the terminal electrodes are brought into contact with the corresponding conductors; and

firing the ceramic green body having the chip electronic component so as to integrate the conductors on the ceramic green body with the corresponding terminal electrodes of the chip electronic component by sintering. (emphasis added)

With the unique combination of features and method steps recited in Applicant's Claim 16, including the step of "mounting a chip electronic component including a ceramic sintered compact defining an element assembly and terminal electrodes on a ceramic green body having conductors thereon such that the terminal electrodes are brought into contact with the corresponding conductors," Applicant has been able to provide a method for manufacturing a chip electronic component-mounted ceramic substrate through which the chip electronic component can be firmly mounted on the ceramic substrate without using any bonding material, such as solder or electroconductive adhesive, and which thus can achieve high-density packaging (see, for example, paragraph [0007] of Applicant's originally filed Substitute Specification).

The Examiner alleged that Sakamoto et al. teaches all of the features recited in Applicant's Claim 16, including the steps of "mounting a chip electronic component (Fig. 1, items 10-12) including a ceramic sintered compact (Fig. 1, 1) defining an element assembly and terminal electrodes (Fig. 3, 19a) on a ceramic green body" and "firing the ceramic green body (Col. 15, lines 14-20) having the chip electronic component so as to integrate the conductors on the ceramic green body with the corresponding terminal electrodes of the chip electronic component by sintering." Applicant respectfully disagrees.

Contrary to the Examiner's allegations, none of the chip electronic components 10-12 of Sakamoto et al. include **a ceramic sintered compact** when they are mounted on/in the ceramic green body 1g. Instead, each of the electronic components 10-12 of Sakamoto et al. include ceramic green sheets when they are mounted on/in the ceramic

green body 1g. Then, after the entire ceramic green body 1g, including the electronic components 10-12, is assembled, the entire ceramic green body 1g is fired to form the sintered multilayer ceramic component.

Particularly, col. 12, lines 49-65 and col. 14, lines 51-54 of Sakamoto et al. disclose:

A compact block for a capacitor containing **a raw ceramic functional material 10g to be the above-mentioned capacitor 10 and a compact block for an inductor containing a raw ceramic functional material 11g to be the inductor 11** are prepared, respectively.

The compact block for a capacitor 10g includes a ceramic dielectric member as the ceramic functional material so as to provide a laminated structure where multi-layer internal conductors 21 **are formed via a raw dielectric sheet 20 containing the ceramic dielectric member**. Terminal electrodes 22 and 23 are formed at end faces of the compact block 10 facing to each other. The internal electrodes 21 are provided such that ones to be connected with the terminal electrode 22 at one side and ones to be connected with the terminal electrode 23 at the other side are arranged alternately as in an internal electrode in a known laminated ceramic capacitor.

...

With the compact blocks 10g and 11g, and the ceramic green sheets 2g to 8g accordingly obtained, a raw composite compact 1g to be the multi-layer ceramic substrate 1 after baking can be produced as follows. (emphasis added)

Thus, Sakamoto et al. clearly fails to teach or suggest the step of “mounting a chip electronic component including a ceramic sintered compact defining an element assembly and terminal electrodes on a ceramic green body having conductors thereon such that the terminal electrodes are brought into contact with the corresponding conductors” as recited in Applicant’s Claim 16.

Accordingly, Applicant respectfully reconsideration and withdrawal of the rejection of Claim 16 under 35 U.S.C. § 102(b) as being anticipated by Sakamoto et al.

Furthermore, Applicant respectfully submits that it would not have been obvious to modify the method of Sakamoto et al. to include the step of “mounting a chip electronic component including a ceramic sintered compact defining an element assembly and terminal electrodes on a ceramic green body having conductors thereon

such that the terminal electrodes are brought into contact with the corresponding conductors” as recited in Applicant’s Claim 16, because Sakamoto et al. fails to teach or suggest anything at all about any ceramic sintered compact which could or should be mounted on a ceramic green body prior to baking or firing, or that there would have been any reason, incentive, or motivation to do so.

In view of the foregoing amendments and remarks, Applicant respectfully submits that Claim 16 is allowable. Claims 17-22 depend upon Claim 16, and are therefore allowable for at least the reasons that Claim 16 is allowable. In addition, Applicant respectfully requests that the Examiner rejoin and allow non-elected Claims 23-25 along with generic Claim 16.

In view of the foregoing amendments and remarks, Applicant respectfully submits that this application is in condition for allowance. Favorable consideration and prompt allowance are solicited.

The Commissioner is authorized to charge any shortage in fees due in connection with the filing of this paper, including extension of time fees, to Deposit Account No. 50-1353.

Respectfully submitted,

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